TEMSCON GLOBAL

Technology Management, Innovation and Leadership for a Sustainable, Flourishing World

August 4–7, 2025
Wyndham San Diego Bayside || San Diego, CA, USA

HTTPS://2025.IEEE-TEMSCON-GLOBAL.ORG

CALL FOR PAPERS

ORGANIZERS

GENERAL CHAIRS

Andrea Belz
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Tariq Samad
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TECHNICAL PROGRAM CHAIRS

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MinBzk, Netherlands

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INDUSTRY CHAIRS

Marc Schlichtner
Siemens Healthineers, Germany

Tarun Soni
Northrop Grumman, US

See the conference website for the full **Operating Committee**

DEADLINES

ABSTRACT AND FULL PAPER SUBMISSION
March 20, 2025

SPECIAL SESSION SUBMISSION
April 1, 2025

WROKSHOP SUBMISSION
April 15, 2025

ACCEPTANCE NOTIFICATION
April 30, 2025

FINAL MANUSCRIPT SUBMISSION
June 15, 2025

Today's world has been profoundly shaped by technological innovation. The scale and impact of technology on tomorrow's world will likely be even greater, with attendant opportunities as well as predicaments. How well we manage technologies and their exploitation will thus substantially determine whether we realize a sustainable and flourishing future for humanity and the planet. From addressing societal challenges to meeting industry needs to facilitating entrepreneurial ventures, addressing imperatives of today and tomorrow will crucially rely on technology management and leadership.

TEMSCON Global is the flagship conference of the IEEE Technology and Engineering Management Society (TEMS) and is a premier venue for research on management, innovation, and leadership across the spectrum of technology, science, and engineering. The conference will convene researchers, managers, practitioners, educators, students, and policy makers to present and discuss new developments in the fields of interest of IEEE TEMS. The conference program will include contributions to this call for papers as well as plenary lectures, invited presentations, innovation and entrepreneurship sessions, and industry forums.

SUBMISSIONS FOR THE TEMSCON GLOBAL PROGRAM

TEMSCON Global welcomes submissions of full papers and extended abstracts. Manuscripts that are accepted and presented will be submitted for inclusion in the IEEE *Xplore®* digital library and indexed by EI/Compendex. Authors of selected full papers will be invited to submit extended versions for potential publication in special issues of IEEE Transactions on Engineering Management and IEEE Engineering Management Review. Proposals for workshops and special sessions are also welcome. Refer to the conference website for further details and submission instructions.

TOPICS OF INTEREST (PARTIAL LIST)

MANAGEMENT OF TECHNOLOGIES
- » Machine learning and generative AI
- » Edge and cloud computing
- » Blockchain and distributed ledgers
- » Cybersecurity and quantum
- » Semiconductors and microelectronics

TECHNOLOGY AND BUSINESS STRATEGY
- » Innovation and entrepreneurship
- » R&D and NPD management
- » Supply chain and operations
- » Digital transformation
- » Intellectual property management

SOCIETAL AND INDUSTRY APPLICATIONS
- » Climate change mitigation and adaptation
- » Sustainability and green tech
- » Smart cities and communities
- » Critical infrastructures and security
- » Smart manufacturing and logistics

GOVERNANCE AND POLICY
- » Science and technology policy
- » Regulation and compliance
- » Ethics of artificial intelligence
- » National industrial policy
- » Technology transfer

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